

Title (en)

PLASMA-TREATMENT DEVICE FOR WAFERS

Title (de)

PLASMA-BEHANDLUNGSVORRICHTUNG FÜR WAFER

Title (fr)

DISPOSITIF DE TRAITEMENT PAR PLASMA DE PLAQUETTES

Publication

EP 3278351 A1 20180207 (DE)

Application

EP 16717581 A 20160401

Priority

- DE 102015004414 A 20150402
- EP 2016057285 W 20160401

Abstract (en)

[origin: WO2016156606A1] The problem addressed by the inventions is that of providing an improved introduction of high-frequency waves into a wafer boat. This problem is solved in that a plasma-treatment device, in particular for semiconductor wafers for semiconductor or photovoltaic applications, is provided, comprising a processing chamber for receiving a wafer boat having a plurality of electrically conductive receiving elements for the wafers, means for controlling or regulating a process gas atmosphere in the processing chamber, and at least one voltage source, which can be connected to the wafer boat via a line guided into the processing chamber. The line is configured as a coaxial line having an inner conductor and an outer conductor, and between the inner conductor and the outer conductor, a dielectric is provided such that when impinged upon with high-frequency voltage, the propagation velocity and the wavelength of the electromagnetic wave in the coaxial conductor are reduced with respect to a corresponding propagation velocity and wavelength of the electromagnetic wave in vacuo.

IPC 8 full level

H01J 37/32 (2006.01)

CPC (source: EP US)

C23C 16/509 (2013.01 - US); **H01J 37/32082** (2013.01 - EP US); **H01J 37/32577** (2013.01 - EP US); **H01J 37/32715** (2013.01 - EP US); **H01L 21/67313** (2013.01 - US); **H01L 21/67326** (2013.01 - US)

Citation (search report)

See references of WO 2016156606A1

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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DOCDB simple family (application)

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